

ASPIDES

WP1 – ASIC design and verification

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ASPIDES: WP1 – ASIC design and verification

WP1: simulation, design and verification of the prototype chip and the demonstrator.

Time: 28 months of the 36 needed by the whole project

Tasks

- Task 1.1 (M1-M2): draft of the specifications for sensors and integrated readout electronics
- Task 1.2 (M3-M16): simulation, layout, verification and production of the prototype chip
- Task 1.3 (M13-M28): simulation, layout, verification and production of the demonstrator chip

Milestones

- M2: specification sheet for sensors and integrated readout electronics drafted
- M10: layout of the prototype chip submitted
- M22: layout of the demonstrator chip submitted

Deliverables

- M2: specification sheet for sensors and integrated readout electronics
- M16: prototype chip
- M28: demonstrator chip

ASPIDES: WP1 – Prototype chip

- **Time:** November 2025 for MPW
- **Budget:** 50 k€ + 5 k€
 - 50 k€ -> LFoundry CMOS 110 nm (2520€/mm²) -> ~ 16 mm² (with 4 metal layer option)
 - 5 k€ -> packaging for 10 chips
- **The metal layer option issue:**
 - M4 option: no extra cost
 - M6 option: 18.800 € extra budgeted (NO VAT) to be shared with the other “M6 users”
 - According to LFoundry the chance to have another M6 customer is 30% (name cannot be disclosed, extra budget sharing is managed by LFoundry)
 - Silicon area using the 50 k€ with M6 option: 8 mm²
 - Silicon area using the 50 k€ + extra with M6 option : total area 16 mm²: ASPIDES 11 mm² + 5 mm² for sponsor

ASPIDES: WP1 - PDK and DEV tools

PDK:

- LF110nm PDK -> latest release 1.3.2 (July 2022)
 - 2 metal layer options available
 - 2 MOS flavours available: 110 nm (1.2 V), 360 nm (3.3 V)
- SPAD Addon -> release 1.0.0 (June 2019) -> provides abstracts and PV rules for 4 different FBK SPADs
-> Is it still needed due to our custom cells?

DEV tools:

- Cadence:
 - INFN has a reduced set of licences shared among the sections -> slow design process
 - PDK for Cadence is better developed -> fast layout drawing
- Synopsys:
 - INFN section local licences -> fast design process
 - PDK not as good as Cadence one -> slow layout drawing
- Calibre:
 - Physical verification: DRC, LVS, ERC

ASPIDES: WP1 – Resources Sharing

A repository/database should be created to share technical documents, design files, manuals, etc:

- The prototype will contain several parts: dSiPM, aSiPM, transistors for cryogenic characterization, electronic blocks and so on:
 - Are we going to create a common database for sharing?
 - Standard IPs (Bandgap, DAC, ADC, SLSV Rx/Tx, etc.), common/personal?
 - In case of sharing, a database to keep the history of all updates could be usefull, Clisoft could be a solution.
- We can use Alfresco for documents, but it's not suitable for design files (usually foundries clearly ask for Clisoft or similar)

ASPIDES: WP1 – Prototype organization

- WP1 participants: BA, BO, PV, TO? How to share the area?
 - We need an estimation of the blocks that each participant wants to prototype
 - 4 equal sections + 1 for common blocks
 - 4 sections of different area + 1 for common blocks
- Prototype organization:
 - One common pad-ring shared among all the structures/blocks
 - Several chiplet (area consumption and extra cost for dicing)



ASPIDES: WP1 – Task 1.1 & Task 1.2

- **Task 1.1 (2 Months):** draft of the specifications for sensors and integrated readout electronics
 1. Collect the specifications starting from the contribution of yesterday (BA, NA, MI)
 2. Organize specifications in a shared table: one column for each application and one row for each specification (time resolution, charge resolution, spatial resolution, area, etc.)
 3. One meeting (online) to discuss and approve the final specification document

- **Task 1.2 (14 Months):** simulation, layout, verification and production of the prototype chip
 - 8 months for design, layout and verification -> prototype assembly and verification 1 month
 - For the design the SPAD model is needed -> is it already available?
 - Floor plan (estimation):
 - Collect the number of blocks, area, pins, power domains (A/D) and consumption.